

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10811999			
<b>Filing Date:</b>	30-Mar-2004			
<b>Title of Invention:</b>	METHOD OF MANUFACTURING A SEMICONDUCTOR PACKAGE USING A LEAD FRAME HAVING THROUGH HOLES OR HOLLOW THEREIN			
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<b>Filer:</b>	Michael J. Scheer/Inga Hildreth			
<b>Attorney Docket Number:</b>	X2007.0158			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	10	3	30
Total in USD (\$)				1730